

THE U.S. PATENT & TRADEMARK OFFICE OFFICIAL MAILROOM STAMP AFFIXED HERETO, ACKNOWLEDGES RECEIPT OF **ENCLOSURES:** Patent (X) Application_ Specification 70 pages (<u>x</u>) Claims_7_pages (\mathbf{x}) (X) Abstract _1_ page(s) (x) Drawing Sheets no. 24 (F) X (INF) (X) Transmittal Letter : New Divisional Apln. (x) Check \$ 750.00 No: 14074 (⋉) Declaration/Oath () Assignment and Cover Sheet (x) Information Disclosure Statement (x) Response/Amendment - Preliminary A () Extension of Time (In Duplicate) () Small Entity Status () Copy of Priority Document Appointment of Associate Attorneys ATTY/SEC: MJM/cn RE: APPLICATION File no: 0553-0166.01 Shunpei YAMAZAKI et al Applicant: S.N.: Not Assigne Filing Date: Herewith Title: Wiring Material and a Semiconductor Device Having a Wiring Using the Material, and the Manufacturing Method Thereof

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re	Application of	
Yama	zaki et al.	
Serial No.:		*Express Mail* Mailing Label No. EV 321709204 Date of Deposit
Filed: Herewith		I hereby certify that this correspondence is being
For:	Wiring Material And A Semiconductor Device Having A Wiring Using the Material, And The Manufacturing Method Thereof	deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR1.10 on the date indicated above and is addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 Name: Value (typed or printed)
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PRELIMINARY AMENDMENT A

Sir:

Alexandria, VA 22313-1450

Prior to examination and calculation of the fees, please amend the above-identified application as follows: